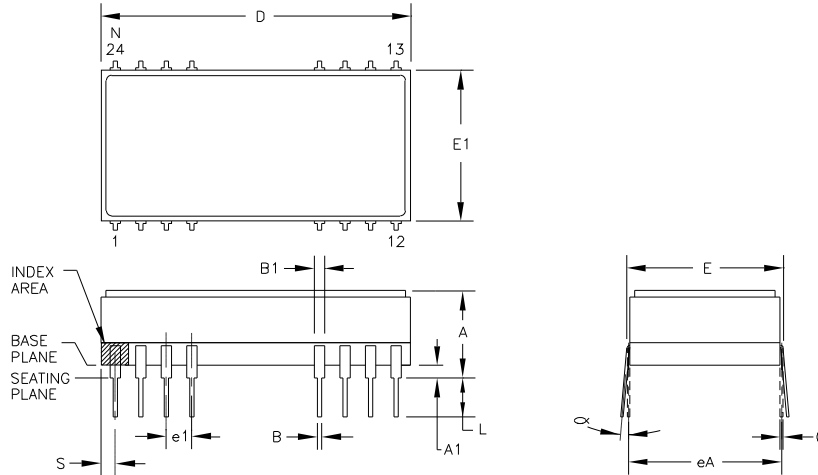


Package Number 231 - 24-Lead Side Braze DIP, .600 Wide, ISO Package



DIM	INCHES		MILLIMETERS		N	E
	MIN.	MAX.	MIN.	MAX.		
A	.310	.375	7.87	9.52		
A1	.040	.060	1.02	1.52		
B	.016	.020	0.41	0.51	5	
B1	.040	TYP.	1.02	TYP.	5	
C	.009	.012	0.23	0.30		
D	1.180	1.265	29.97	32.13		
E	.600	.620	15.24	15.75		
E1	.570	.610	14.48	15.49	6	
e1	.100	TYP.	2.54	TYP.	2	
eA	.580	.620	14.73	15.75	2	
L	.125	.180	3.18	4.57		
N	16		16		4	
S	.044	.056	1.12	1.42		
α	0°	15°	0°	15°	3	

- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5-1982.
 2. LEADS WITHIN .005 IN. (0.13mm) RADIUS OF TRUE POSITION (TP) AT GAUGE PLANE WITH MAXIMUM MATERIAL CONDITION AND UNIT INSTALLED.
 3. α APPLIES TO SPREAD LEADS PRIOR TO INSTALLATION.
 4. N IS THE NUMBER OF TERMINAL POSITIONS.

5. OUTLINES ON WHICH THE SEATING PLANE IS COINCIDENT WITH THE PLANE (A1 = 0), TERMINALS LEAD STANDOFFS ARE NOT REQUIRED, AND B1 MAY EQUAL B ALONG ANY PART OF THE LEAD ABOVE THE SEATING/BASE PLANE.
6. E1 DOES NOT INCLUDE PARTICLES OF PACKING MATERIALS.
7. CONTROLLING DIMENSION: INCH.
8. A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN THE CROSS-HATCHED AREA.

PACKAGE NUMBER: ZZ231 REV.: E
 JEDEC NUMBER: NONE



PACKAGE DRAWING

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